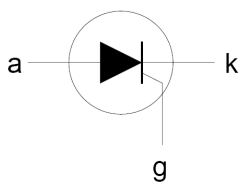


/ Descriptions

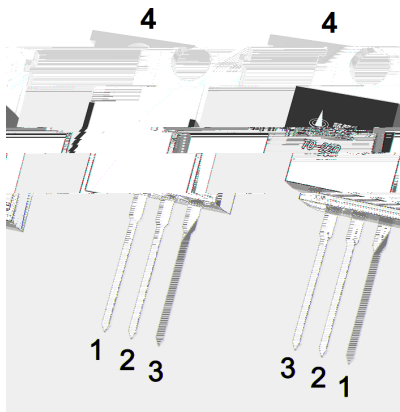
/ Features

/ Applications

/ Equivalent Circuit



/ Pinning



/ Marking

\leq °C			
°C			
°C			
μ			
		~	
		~	

/ Electrical Characteristic Curve

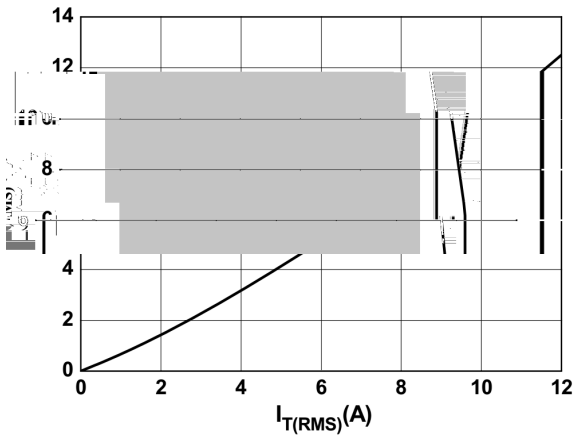


FIG.1 Maximum power dissipation versus RMS on-state current

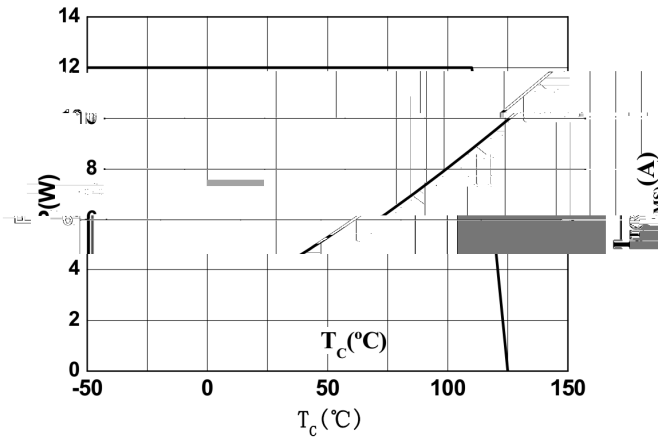


FIG.2: RMS on-state current versus case temperature

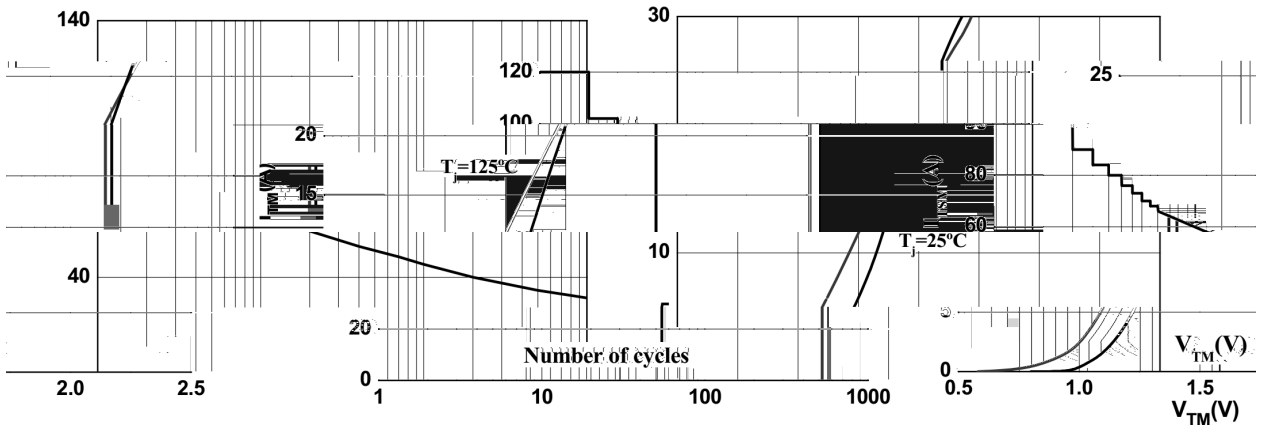


FIG.3: Surge peak on-state current versus number of cycles

FIG.4: On-state characteristics

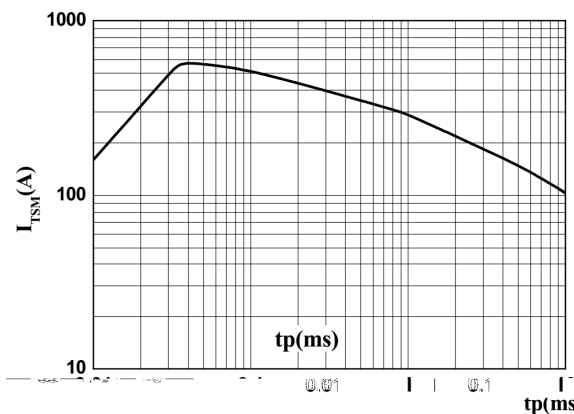


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width $t_p < 20\text{ms}$, and corresponding value of I_2t ($di/dt < 100\text{A}/\mu\text{s}$)

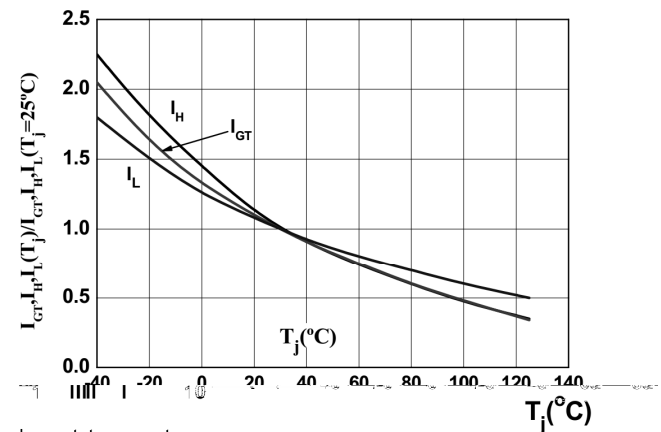


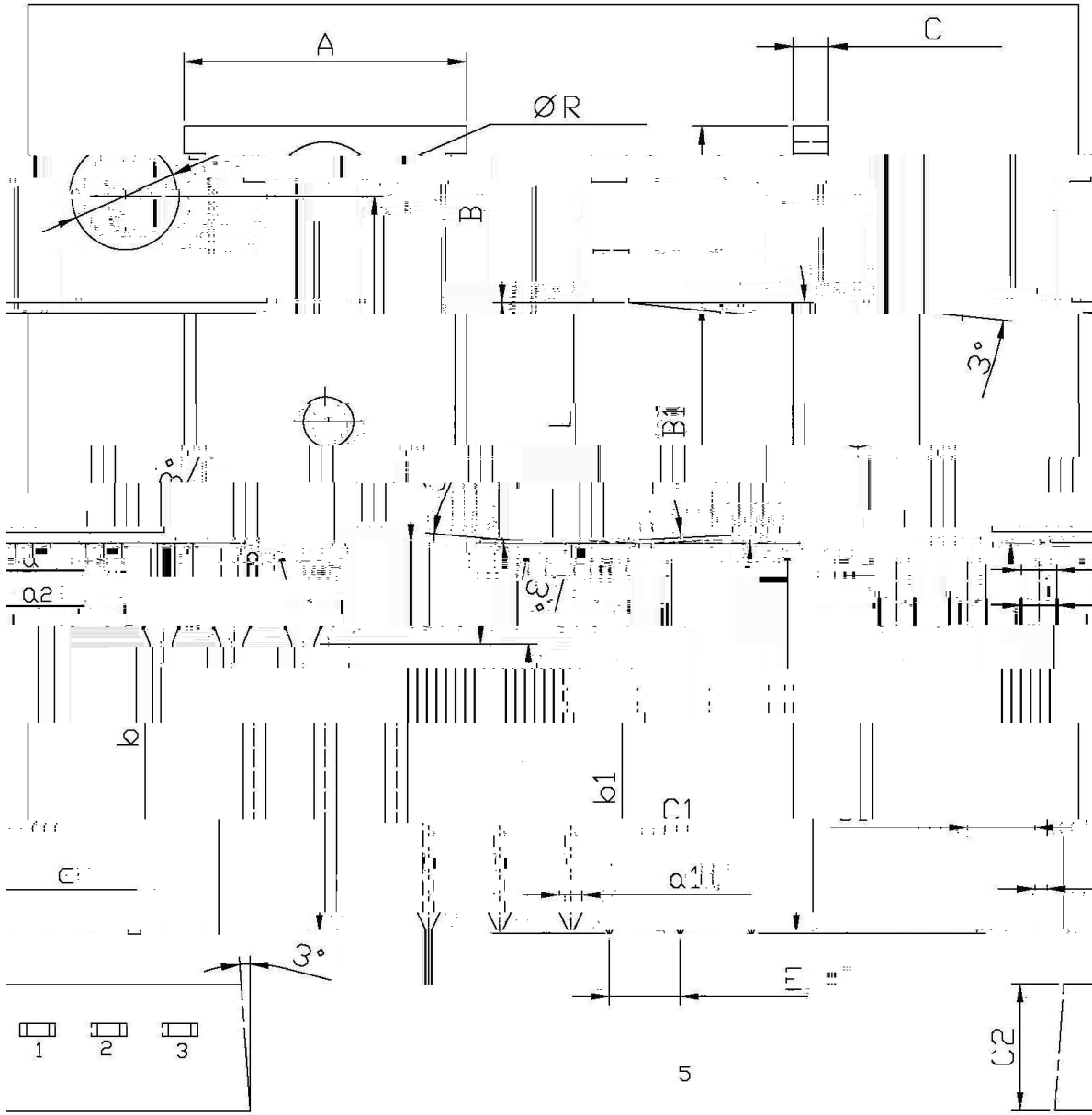
FIG.6: Relative variations of gate current, holding current and latch current versus junction temperature

ite trigger
ing current
e

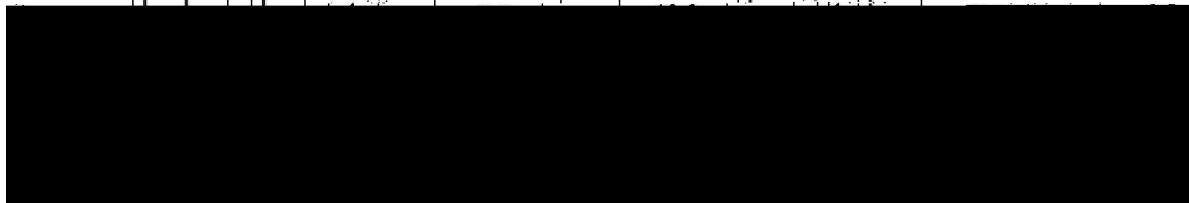
/ Package Dimensions

TO-220

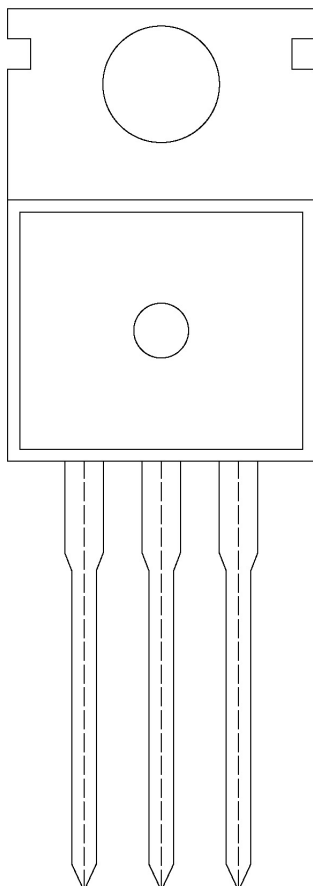
单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	9.8	10.2	C	12	14
R	3.56	3.64	B	6.3	6.7
B1	15.7	16.1	B1	9.0	9.4
b	12.6	13.6	C1	2.2	2.6



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)

/ Resistance to Soldering Heat Test Conditions

℃

/ Packaging SPEC.
